

P-Ch MOSFET

#### **General Description**

The WSF50P10 is the highest performance trench P-ch MOSFET with extreme high cell density , which provide excellent RDSON and gate charge for most of the synchronous buck converter applications .

The WSF50P10 meet the RoHS and Green Product requirement,100% EAS guaranteed with full function reliability approved.

#### Features

- Advanced high cell density Trench technology
- Super Low Gate Charge
- Excellent CdV/dt effect decline
- 100% EAS Guaranteed
- Green Device Available

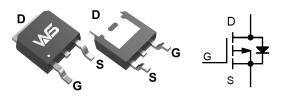
#### **Product Summery**

BVDSS	RDSON	ID
-100V	40mΩ	-34A

#### **Applications**

• Power Management for Industrial DC / DC Converters.

#### **TO-252 Pin Configuration**



#### Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
V <sub>DS</sub>	Drain-Source Voltage	-100	V
V <sub>GS</sub>	Gate-Source Voltage	±20	V
I <sub>D</sub> @T <sub>C</sub> =25℃	Continuous Drain Current, -V <sub>GS</sub> @ -10V	-34	A
I <sub>D</sub> @T <sub>C</sub> =100℃	Continuous Drain Current, -V <sub>GS</sub> @ -10V -22		A
I <sub>DM</sub>	Pulsed Drain Current	-136ª	A
E <sub>AS</sub> c	Single Pulse Avalanche Energy	182	mJ
I <sub>AS</sub> <sup>c</sup>	Avalanche Current	-27	A
P₀@T₀=25℃	Total Power Dissipation 96		W
T <sub>STG</sub>	Storage Temperature Range -55 to 150		°C
TJ	Operating Junction Temperature Range	-55 to 150	°C

#### **Thermal Data**

Symbol	Parameter	Typ. Max.		Unit	
R <sub>θJA</sub> <sup>b</sup>	Thermal Resistance Junction-Ambient		60	°C/W	
R <sub>θJC</sub>	Thermal Resistance Junction-Case		1.3	°C/W	

Note a : Pulse width is limited by max. junction temperature.

Note b : Surface Mounted on  $1in^2$  pad area.

Note c : UIS tested and pulse width are limited by maximum junction temperature 150°C(initial temperature T<sub>J</sub>=25°C).



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## Electrical Characteristics (T\_J=25 ~ $\subset$ , unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	$V_{GS}$ =0V , I <sub>D</sub> =-250uA	-100			V
$\triangle BV_{DSS} / \triangle T_J$	BV <sub>DSS</sub> Temperature Coefficient	Reference to 25 $^\circ\!{\rm C}$ , I_D=-1mA		-0.021		V/℃
R <sub>DS(ON)</sub> <sup>d</sup>	Static Drain-Source On-Resistance	V <sub>GS</sub> =-10V , I <sub>D</sub> =-18A		32	40	- mΩ
I US(ON)		V <sub>GS</sub> =-4.5V , I <sub>D</sub> =-10A		38	51	
V <sub>GS(th)</sub>	Gate Threshold Voltage		-1.0	-2.0	-3.0	V
$ riangle V_{GS(th)}$	V <sub>GS(th)</sub> Temperature Coefficient	$V_{\rm GS} = V_{\rm DS}$ , $I_{\rm D} = -2500$ A		4.08		mV/℃
la sa	Drein Course Lookage Current	$V_{\text{DS}}\text{=-80V}$ , $V_{\text{GS}}\text{=}0\text{V}$ , $T_{\text{J}}\text{=}25^\circ\!\!\mathrm{C}$			-1	uA
I <sub>DSS</sub>	Drain-Source Leakage Current	V <sub>DS</sub> =-80V , V <sub>GS</sub> =0V , T <sub>J</sub> =85℃			-30	uA
I <sub>GSS</sub>	Gate-Source Leakage Current	$V_{GS}=\pm20V$ , $V_{DS}=0V$			±100	nA
Qg <sup>e</sup>	Total Gate Charge			56		
Q <sub>gs</sub> e	Gate-Source Charge	V <sub>DS</sub> =-30V , V <sub>GS</sub> =-10V , I <sub>D</sub> =-18A		9.5		nC
Q <sub>gd</sub> e	Gate-Drain Charge			14.5		
T <sub>d(on)</sub> e	Turn-On Delay Time			17		
Tr <sup>e</sup>	Rise Time	$V_{DD}$ =-30V , $V_{GS}$ =-10V ,		9		ns
T <sub>d(off)</sub> e	Turn-Off Delay Time	R <sub>G</sub> =6Ω, I <sub>D</sub> =-1Α ,RL=30Ω.		83		115
T <sub>f</sub> e	Fall Time			34		
C <sub>iss</sub> e	Input Capacitance	V <sub>DS</sub> =-50V , V <sub>GS</sub> =0V , f=1MHz		2480	3207	
C <sub>oss</sub> <sup>e</sup>	Output Capacitance			268		pF
Crss <sup>e</sup>	Reverse Transfer Capacitance			126		

#### **Diode Characteristics**

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
Is	Continuous Source Current	VG=VD=0V, Force Current			-18	А
V <sub>SD</sub>	Diode Forward Voltage	$V_{GS}\text{=}0V$ , $I_{S}\text{=}\text{-}18A$ , $T_{J}\text{=}25^{\circ}\!\mathbb{C}$			-1.2	V

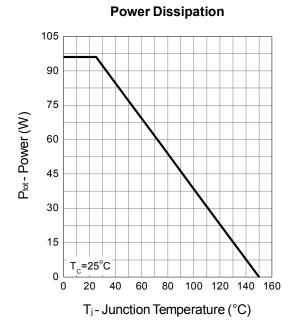
Note d : Pulse test ; pulse width $\leq$ 300µs, duty cycle $\leq$ 2%.

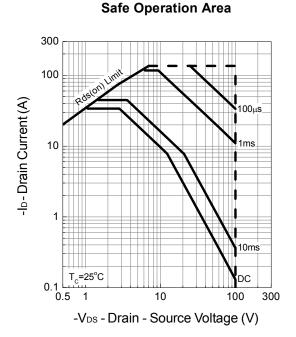
Note e : Guaranteed by design, not subject to production testing.



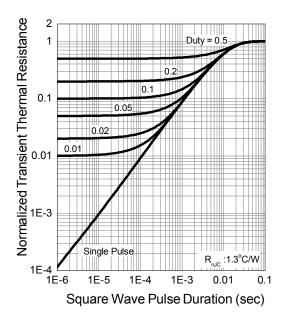
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### **Typical Characteristics**





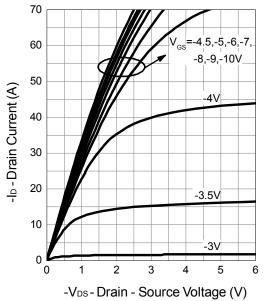
**Thermal Transient Impedance** 



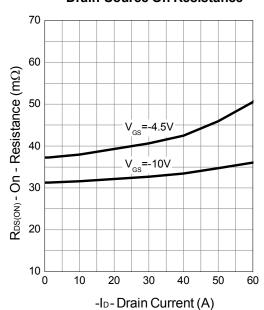
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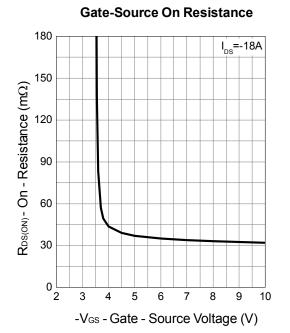
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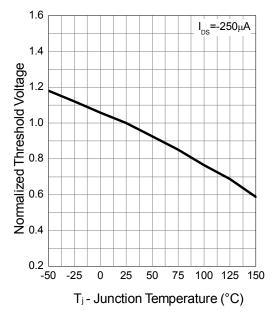
Output Characteristics



Drain-Source On Resistance

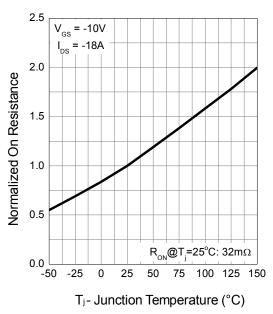


Gate Threshold Voltage

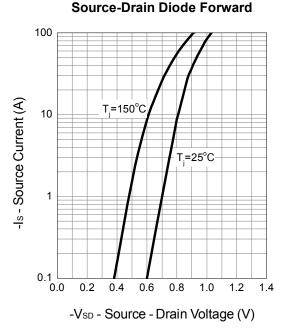




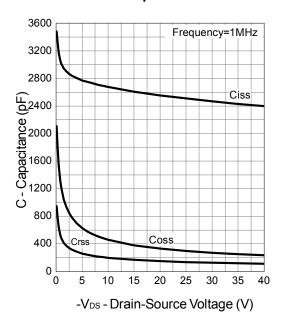
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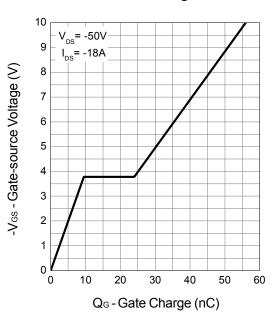
**Drain-Source On Resistance** 



Capacitance

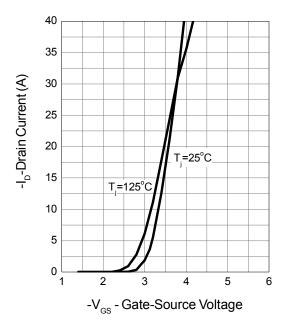


Gate Charge





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#### Transfer Characteristics



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